

Report No. MCR-22-0328 April 26,2022

RENESAS SEMICONDUCTOR RELIABILITY REPORT

GROUP : S3A1

DEVICE : R7FS3A1XXX

APPLICATION: Consumer / Industry

Quality Assurance Div. Renesas Electronics Corporation



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Table. Reliability test results (QFP)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 $℃$ to 150 $ℂ$, 300 cycles	0/22	
Latch-Up JESD78 Pulse Current Injecti		Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

^{*1)} With preconditioning per JESD22-A113, MSL 3
•It is tested to confirm that all the samples are satisfied with an individual product specification.



Table. Reliability test results (QFN)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 $℃$ to 150 $ℂ$, 300 cycles	0/22	
Latch-Up (LU) JESD78 Pulse Current Injecti		Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

^{*1)} With preconditioning per JESD22-A113, MSL 3
•It is tested to confirm that all the samples are satisfied with an individual product specification.



Table. Reliability test results (BGA)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 $^{\circ}$ to 125 $^{\circ}$, 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

^{*1)} With preconditioning per JESD22-A113, MSL 3

Note:

[•]It is tested to confirm that all the samples are satisfied with an individual product specification.



Table. Reliability test results (LGA)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 $^{\circ}$ to 125 $^{\circ}$, 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

^{*1)} With preconditioning per JESD22-A113, MSL 3

Note :

[•]It is tested to confirm that all the samples are satisfied with an individual product specification.

The failure rate of the device in an actual use condition can be estimated by the below procedure.

•Equation for the failure rate estimation (λ)

$$\lambda = \lambda b \times \pi T$$
 (FIT)

①Unique failure rate (λ b)

$$\lambda b = 3.8 \text{ FIT}$$

Unique failure rate at Ta=55 ℃ using 60 % confidence level.

②Temperature term (π T)

$$\pi T = \exp\{11600 \times Ea \times (1/(273+55)-1/(273+Ta))\}$$

Ea: Activation energy (eV) Ta: Ambient temperature ($^{\circ}$ C)

π T simplified chart as Ea=0.7 eV												
Ta (℃)	40	50	55	60	65	70	75	80	85	90	100	110
πТ	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

·MTTF (Mean Time To Failure)

$$MTTF = 1/\lambda$$



Reference about Renesas package code

Package type	Package code *1	
Lead type plastic package	QFP	PxQP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG

^{*1.} First four digit

Table. Product list

Table	e. Product lis						
No	Group	Product part number	Package code	No	Group	Product part number	Package code
1	S3A1	R7FS3A17C2A01CBJ	PLBG0121J*	51			
2	S3A1	R7FS3A17C3A01CFB	PLQP0144K*	52			
3	S3A1	R7FS3A17C3A01CFM	PLQP0064K*	53			
4	S3A1	R7FS3A17C3A01CFP	PLQP0100K*	54			
5	S3A1	R7FS3A17C2A01CLJ	PTLG0100J*	55			
6	S3A1	R7FS3A17C2A01CLK	PTLG0145K*	56			
7	S3A1	R7FS3A17C3A01CNB	PWQN0064L*	57			
8	33/11	1071 337 (17 337 (013)	1 WQNOOO IL	58			
9				59			
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41				91			
42				92			
43				93			
44				94			
45				95			
46				96			
47				97			
48	1		1	98			
49				99			
50				100			
50	1	1		100	1	<u> </u>	1